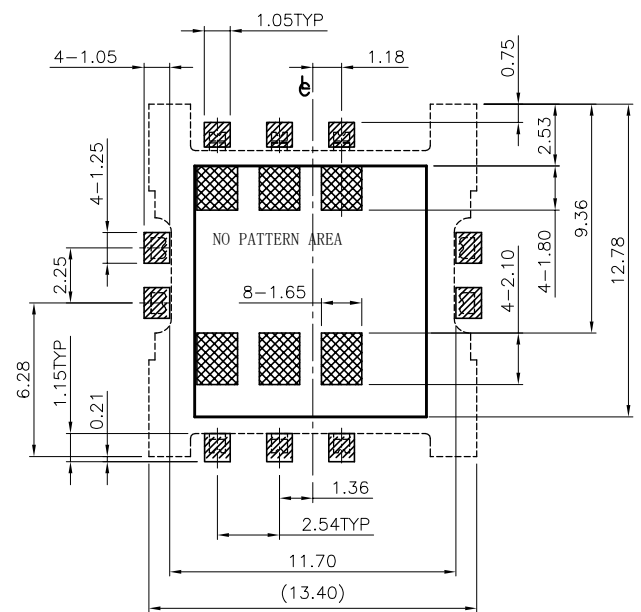
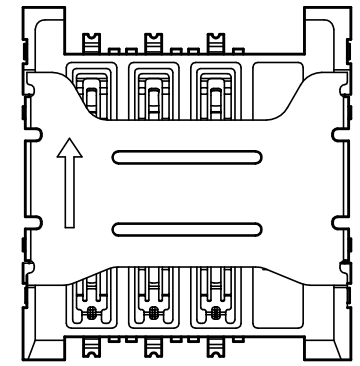
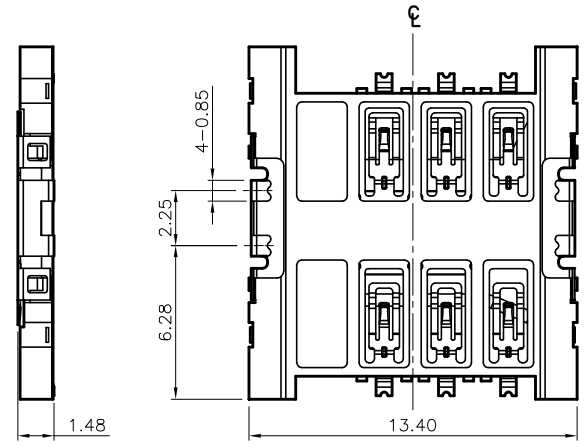
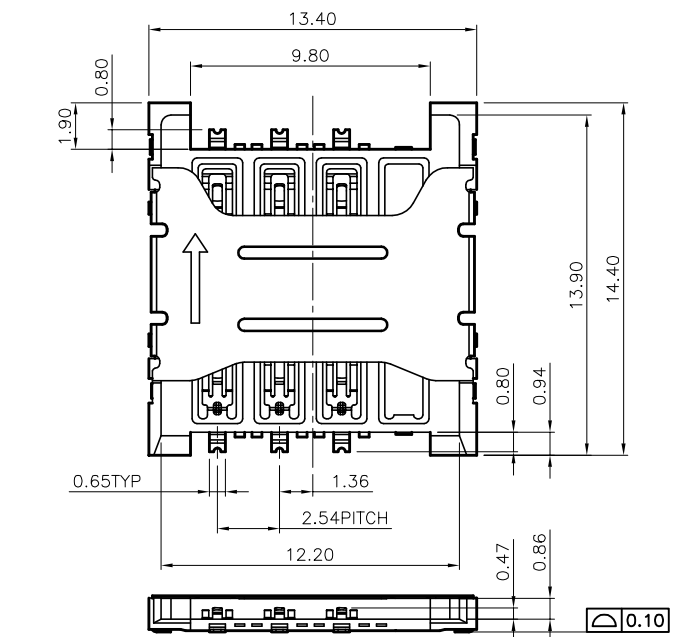
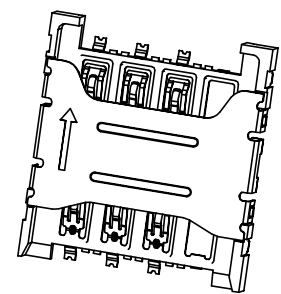


REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2011/10/31



RECOMMENDED P.C.B. LAYOUT
TOLERANCE:±0.05 TOP VIEW

- PCB AREA
- CONNECT AREA
- KEEP OUT AREA



MATERIALS

1. HOUSING : THERMOPLASTIC (UL 94V-0) .
2. TERMINAL : COPPER ALLOY,
PLATING : GOLD PLATED ON CONTACT AREA
AND SOLDER TAILS,NICKEL PLATED OVERALL.
3. SHELL : STAINLESS STEEL.
PLATING : NICKEL PLATED OVERALL.
GOLD PLATED ON SOLDER TAILS

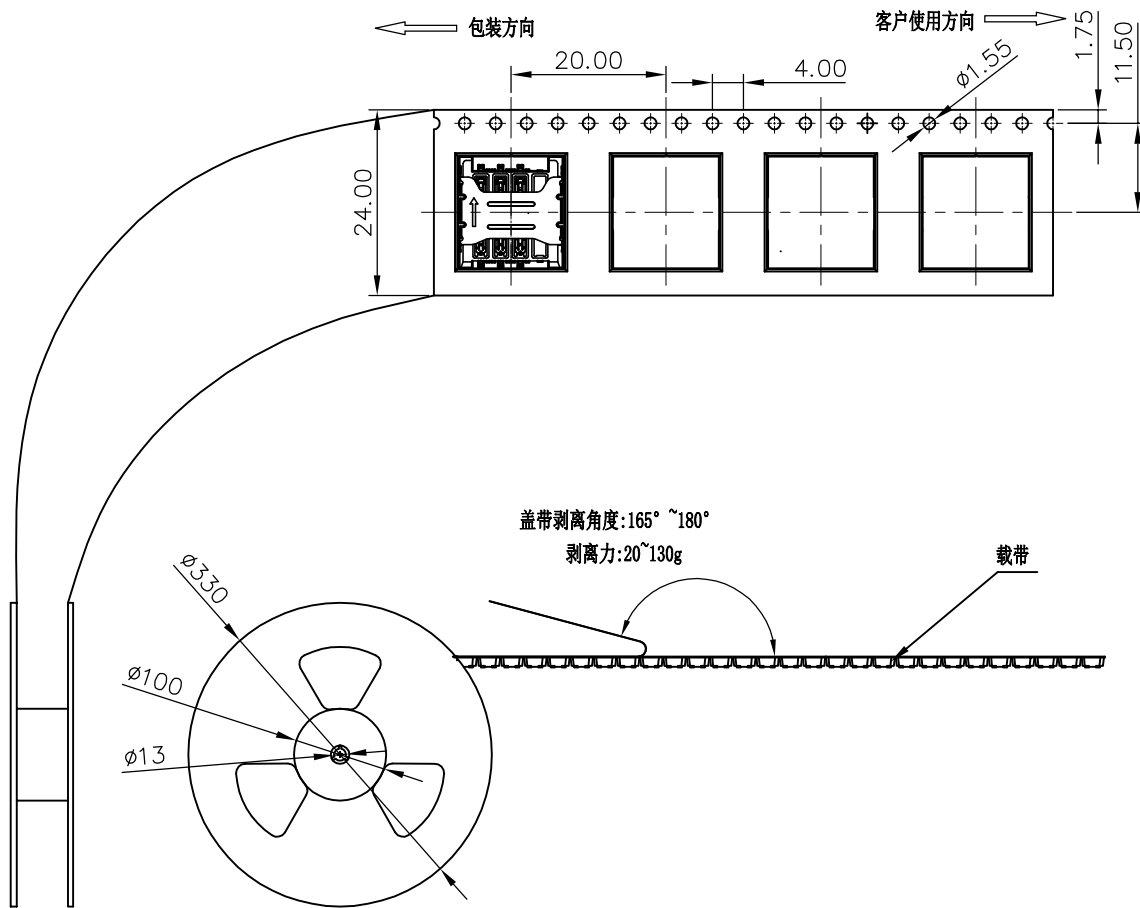
SPECIFICATION

1. CURRENT RATING : 1.0 A MAX.
2. DIELECTRIC WITHSTANDING VOLTAGE :
500V AC R.M.S. FOR ONE MINUTE.
3. INSULATION RESISTANCE : 1000M次MIN. AT 500V DC.
4. CONTACT RESISTANCE : 30m 次MAX.
5. OPERATING TEMPERATURE : -40°C TO +85°C.

DESCRIPTION OF PLATING ON TERMINALS			
NO.	EXPLAIN	NO.	EXPLAIN
0	GOLD FLASH	3	GOLD 15u"
1	GOLD 5u"	4	GOLD 20u"
2	GOLD 10u"	6	GOLD 30u"

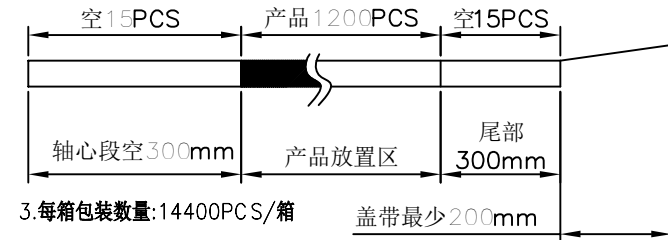
GENERAL TOLERANCE		DWG NO.	JYSA0422-001	APPD:	WIND	Scale	1:1
X.±0.45	x.'±5'	Title	MICRO SIM SOCKET 6PIN 1.50H (焊接脚内折防浪PIN)	CHKD:		UNIT	mm
.X±0.35	.x'±2'			DR:			
.XX±0.25	.xx'±1'	Part NO.	JYS-SIM150-090	Date	2012/02/29		
.XXX±0.15	.xxx'±0.5'						
SHEET	1/1			Shenzhen JYCONN Electronics Co., LTD.			

REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2012/04/13

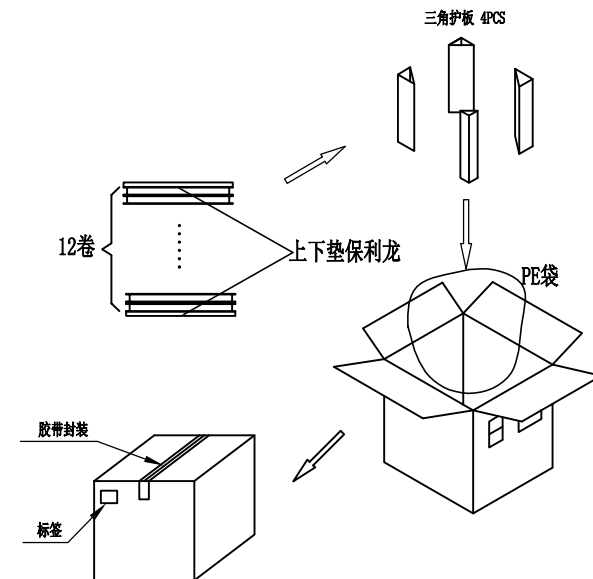


NOTES

1. 每卷包装数量: 1200PCS/每卷
2. 卷带包装方式:



3. 每箱包装数量: 14400PCS/箱 盖带最少200mm
4. 纸箱规格: 340*340*390MM, 材质: K=K



GENERAL TOLERANCE		DWG NO.	JYSA0521-018	APPD:	WIND	Scale	1:1
X.±0.45	x.*±5'	Title	MICRO SIM CARD 6P 1.5H 包装图	CHKD:		UNIT	mm
.X±0.35	.x*±2'			DR:			
.XX±0.25	.xx*±1'	Part NO.		Date	2012/04/13		
.XXX±0.15	.xxx±0.5'						
SHEET	1/1			Shenzhen JYSCONN Electronics Co., LTD.			